

## **Application Data Sheet**

### **Application Information**

<b>Application Type::</b>	Regular
<b>Subject Matter::</b>	Utility
<b>CD-ROM or CD-R?::</b>	None
<b>Computer Readable Form (CRF)?::</b>	No
<b>Title::</b>	CONTACT PROBE STORAGE FET SENSOR AND WRITE HEATER ARRANGEMENTS
<b>Attorney Docket Number::</b>	200310973-1
<b>Request for Early Publication?::</b>	No
<b>Request for Non-Publication?::</b>	No
<b>Suggested Drawing Figure::</b>	1
<b>Total Drawing Sheets::</b>	7
<b>Small Entity?::</b>	No
<b>Petition included?::</b>	No
<b>Secrecy Order in Parent Appl.?::</b>	No

### **Applicant Information**

<b>Applicant Authority Type::</b>	Inventor
<b>Primary Citizenship Country::</b>	US
<b>Status::</b>	Full Capacity
<b>Given Name::</b>	Robert G.
<b>Family Name::</b>	MEJIA
<b>City of Residence::</b>	Boise
<b>State or Province of Residence::</b>	ID
<b>Country of Residence::</b>	US
<b>Street of mailing address::</b>	3205 N. 24th St.

**Street of mailing address::** 3205 N. 24th St.  
**City of mailing address::** Boise  
**State or Province of mailing address::** ID  
**Postal or Zip Code of mailing address::** 83702

**Applicant Authority Type::** Inventor  
**Primary Citizenship Country::** US  
**Status::** Full Capacity  
**Given Name::** Richard Lee  
**Family Name::** HILTON  
**City of Residence::** Boise  
**State or Province of Residence::** ID  
**Country of Residence::** US  
**Street of mailing address::** 3332 N. Lena Pl.  
**City of mailing address::** Boise  
**State or Province of mailing address::** ID  
**Postal or Zip Code of mailing address::** 83713

#### **Correspondence Information**

**Correspondence Customer Number::** 22879

#### **Representative Information**

<b>Representative Customer Number::</b>	22879	
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**Domestic Priority Information**

<b>Application::</b>	<b>Continuity Type::</b>	<b>Parent Application::</b>	<b>Parent Filing Date::</b>

**Foreign Priority Information**

<b>Country::</b>	<b>Application number::</b>	<b>Filing Date::</b>	<b>Priority Claimed::</b>

**Assignee Information**

**Assignee name::** HEWLETT-PACKARD DEVELOPMENT CO.